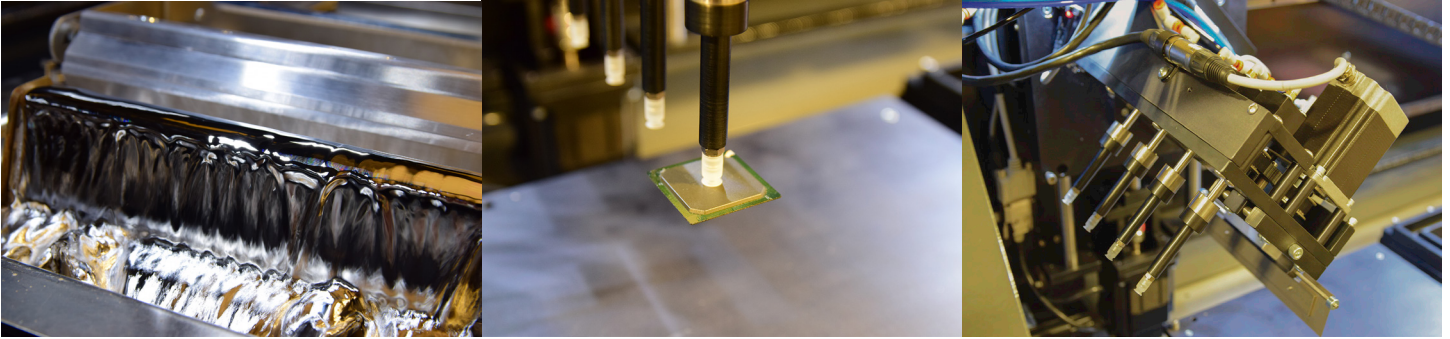


LEAD TINNING MACHINES

CELEBRATING MORE THAN 25 YEARS IN THE AUTOMATED SOLDERING INDUSTRY



 **HENTEC**
INDUSTRIES

RPS



Proudly made in the USA

LEAD TINNING MACHINES

Odyssey 925

Purpose: Mid Volume Production
Manual Load

Performance: High Precision
High Repeatability

Footprint: 54 x 26 x 24" (D x L x H)

Stations: Up to 4 Stations

Solder Capacity: 2 x 40 lbs | 2 x 18.1 kgs

Static Range: 5 x 8 x 4" | 125 x 200 x 100 mm

Dynamic Range: 4 x 4 x 2.5" | 100 x 100 x 64 mm

Flux Static Range: 4 x 4 x 2.5" | 100 x 100 x 64 mm



Odyssey 1325

Purpose: High Volume
High Mix Capacity

Performance: High Precision
High Repeatability

Footprint: 74 x 44 x 55" (D x L x H)

Stations: Up to 6 Stations

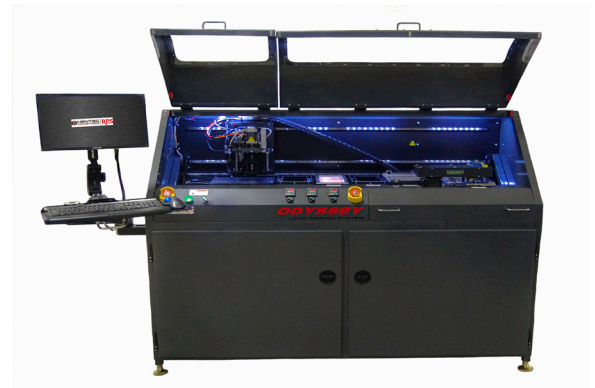
Solder Capacity: 280 lbs | 127 kgs

Static Range: 5 x 8 x 4" | 125 x 200 x 100 mm

Dynamic Range: 5 x 8 x 2.5" | 127 x 200 x 64 mm

Flux Static Range: 5 x 8 x 2.5" | 127 x 200 x 64 mm

3rd Station Preheat: Standard | 4 x 8" (W x L)



Odyssey 1750

Purpose: High Volume
High Mix Capacity
Dual Alloy Capable

Performance: High Precision
High Repeatability

Footprint: 94 x 44 x 55" (D x L x H)

Stations: Up to 8 Stations

Solder Capacity: 280 lbs | 127 kgs

Static Range: 5 x 8 x 4" | 125 x 200 x 100 mm

Dynamic Range: 5 x 8 x 2.5" | 127 x 200 x 64 mm

Flux Static Range: 5 x 8 x 2.5" | 127 x 200 x 64 mm

3rd Station Preheat: Standard | 4 x 8" (W x L)



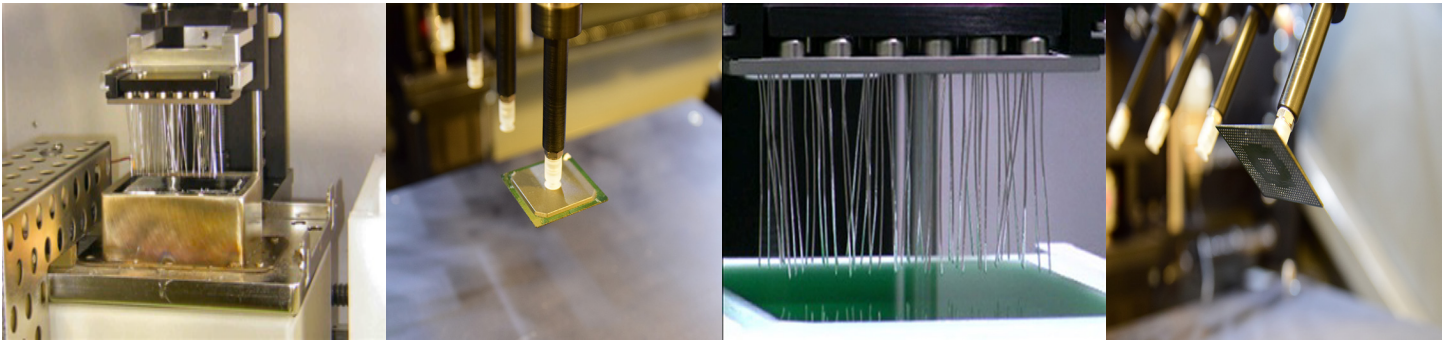
STANDARD FEATURES

- Steel welded frame
- Integrated computer
- Unlimited programs
- Interpolated X and Z rotation motion control
- PID temperature control
- Low dross/ low maintenance
- High repeatability
- Lead free compatible
- High Precision $\pm .002"$ (0.025 mm)
- CE certified
- Mill spec compliant
- Two year system warranty
- Four year solder pot warranty

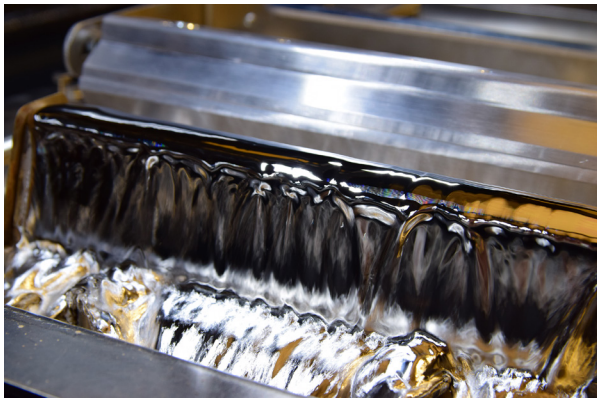
ADDITIONAL OPTIONS

- Single or multi-pot stations
- Dynamic or static solder bath
- Dynamic or static flux bath
- Preheat station
- Rotary Vacuum
- N2 insertion
- Extended warranty
- Auto load/unload (Odyssey 1325 and 1750 only)
- Dual DSP (Odyssey 1750 only)
- Dual flux (Odyssey 1750 only)
- Dual alloy capable (Odyssey 1750 only)

For over 25 years, Hentec Industries has been advancing lead tinning and soldering technology for the military, aerospace, and the commercial micro-electronics component industry. Hentec lead tinning systems are automated, hands-free robotic platforms, designed to tin component leads for re-conditioning and re-tinning applications, including high reliability and military application. Lead tinning systems are suitable for DIP, SIP, QFP, BGA, axial transistor, radial components, and more. Hentec offers several models of the Odyssey system. Each model provides increasing scale and features for higher production volumes and component capacity. Standard features include flux and solder stations, configurable for multiple solder stations, preheat, dynamic or static solder baths, dynamic or static dip flux baths, and rinse and dry stations. Hentec software provides total control to set all process parameters, including immersion depths, dwell times, impeller speeds, insertion and extraction speed acceleration, and all I/O. All systems are designed to meet the needs of small lot batch processing as well as high volume production. Option availability is extensive and includes dynamic or static solder pots, multiple dip stations, dip or drag solder nozzles, standard and custom component tool holders, hot N₂ air knife, and much more.



LEAD TINNING STANDARDS AND COMPLIANCE



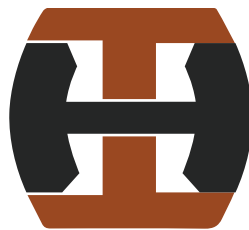
Hentec lead tinning machines are used for lead stripping, tinning of SMT, through-hole RoHS and tin/lead components. The growth of tin whiskers has re-emerged as a threat to the health and safety of electronic systems worldwide with the introduction of RoHS compliant electronic components. Governments and industry have joined together to develop a standard for the replacement on tin only finishes with a proven tin/lead solder. That standard, GEIA-STD-006, provides for a highly controlled robotic hot solder dip that replaces the tin only finish with a tin/lead finish. Hentec provides leadership in meeting the industry and military solderability cleanliness compliance requirements (depending on configuration) for: GEIA-STD-006, MIL-PRF-38535, MIL-PRF-38534E, and ANSI-J-STD-002.

SUCCESS IN THE FIELD

*"Thanks again. I have never seen a company with such great customer service."
- Josh Wilson, 4 Star Electronics*

*"We selected Hentec over several other vendors. The company showed the expertise and the commitment to meet our specific requirements. The Hentec lead tinning system is a great addition to our production environment."
- Lead Tinning Manager, Honeywell*

GLOBAL DISTRIBUTORS: United States, Canada, Australia, Brazil, China, Europe, Mexico, Phillipines, Russia, South Korea, United Kindom, Israel, Italy, France



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